

Electrical Characteristics

Part Number	Device Specifications (at 25°C)							Life Ratings																																					
	DC Breakdown in Volts (@100V/s)			Impulse Break-down in Volts (@100V/μs)	Impulse Break-down In Volts (@1 Kv/μsec)	Insulation Resistance	Capacitance (@1MHz)	Arc Voltage (on state Voltage) @1Amp Min	Surge Life (@500A 10/1000μs)	Nominal Impulse Discharge Current (8/20μs)	Nominal AC Discharge Current (10x1sec @50-60Hz)	AC Discharge Current (9 cycle @50Hz)	DC Holdover Voltage ²	Max Impulse Discharge Current (1 Application @ 10/350μs)																															
	MIN	TYP	MAX	MAX		MIN	MAX	TYP					TYP																																
CG75	60	75	90	400	650	10 ¹⁰ Ω (at 50V)	1.5 pf	15 V	400 shots	5 shots (@20kA)	20 A	100 A	52 V	4kA																															
CG90	72	90	108	400	600								80 V	2.5kA																															
CG90 SN	72	90	108	400	600										135 V	2.5kA																													
CG110	88	110	132	450	600	10 ¹⁰ Ω (at 100V)											2.5kA																												
CG2145	116	145	174	500	600													10 ¹⁰ Ω (at 100V)	2.5kA																										
CG2145 SN	120	145	174	500	600															10 ¹⁰ Ω (at 100V)	2.5kA																								
CG2230 ¹	195	230	265	600	700																	10 ¹⁰ Ω (at 100V)	2.5kA																						
CG2230 SN ¹	184	230	276	600	700																			10 ¹⁰ Ω (at 100V)	2.5kA																				
CG2250	213	250	288	625	725																					10 ¹⁰ Ω (at 100V)	2.5kA																		
CG2250 SN	200	250	300	625	725																							10 ¹⁰ Ω (at 100V)	2.5kA																
CG2300	255	300	345	700	800																									10 ¹⁰ Ω (at 100V)	2.5kA														
CG2300 SN	240	300	360	700	800																											10 ¹⁰ Ω (at 100V)	2.5kA												
CG2350	297	350	403	750	900																													10 ¹⁰ Ω (at 100V)	2.5kA										
CG2350 SN	280	350	420	750	900																															10 ¹⁰ Ω (at 100V)	2.5kA								
CG2420	357	420	483	800	1000																																	10 ¹⁰ Ω (at 100V)	2.5kA						
CG2470 ¹	400	470	540	850	1200																																			10 ¹⁰ Ω (at 100V)	2.5kA				
CG2470 SN ¹	376	470	564	850	1200																																					10 ¹⁰ Ω (at 100V)	2.5kA		
CG2600 ¹	510	600	690	1000	1400																																							10 ¹⁰ Ω (at 100V)	2.5kA
CG2600 SN ¹	480	600	720	1000	1400																																								
CG2800 ¹	680	800	920	1200	1500	10 ¹⁰ Ω (at 100V)				2.5kA																																			
CG21000 ¹	850	1000	1150	1500	1600						10 shots (@10kA)	10 A	65 A	2.5kA																															

NOTES:

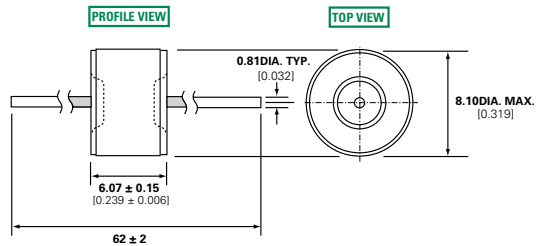
1. Certified to UL 1449.
2. Reference REA PE-80, 0.2A. Tested to ITU-T Rec K.12 and REA PE 80 < 150 mSec.
3. 5 x [5 (+) or 5 (-)] applications 20kA 8/20μSec. (75 to 600 volt devices.)
 10 x [5 (+) and 5 (-)] applications 10kA 8/20μSec. (800 and 100 volt devices.)

Product Characteristics

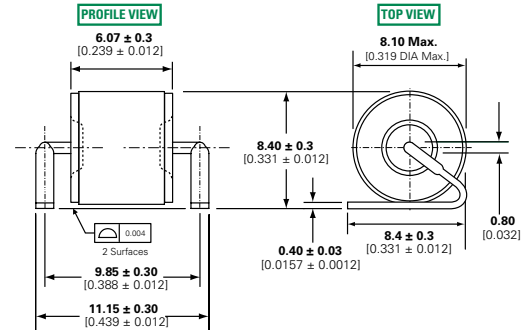
Materials	LS, Axial: Device: Tin Plated 2–5 Microns Lead Wires: Tin Plated 17.5 ± 12.5 Microns Construction: Ceramic Insulator	Glow to arc transition current	< 0.5Amps
	Core: Device: Tin Plated 17.5 ± 12.5 Microns. Construction: Ceramic Insulator	Glow Voltage	60-160 Volts
Product Marking	MS: Device: Dull Tin Plated 7–9 Microns Construction: Ceramic Insulator	Storage and Operational Temperature	-40 to +90
	LF Logo, Voltage and date code; Black in positive print	Maximum Follow On Current¹	230 Volts r.m.s, 200 Amps. (800V and 1000V devices tested to UL1449 3rd edition)

Device Dimensions

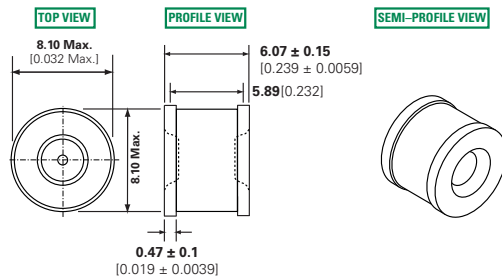
Leaded 'L' Type Straight Axial Devices



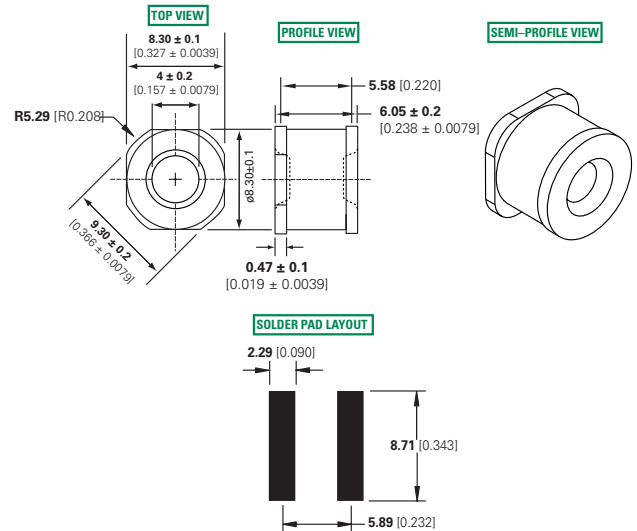
Leaded 'LS' Type Shaped Lead Devices



Core Devices

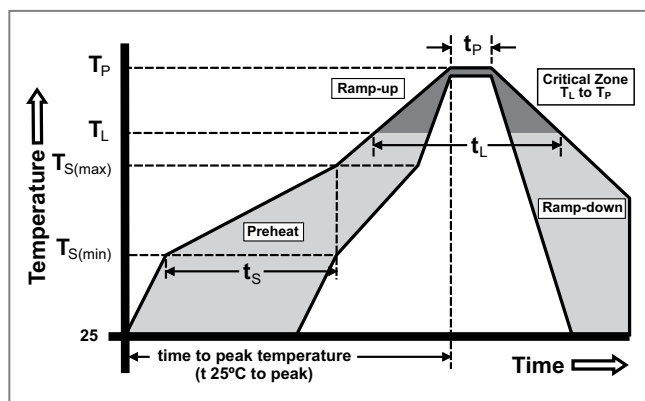


'MS' Type Devices

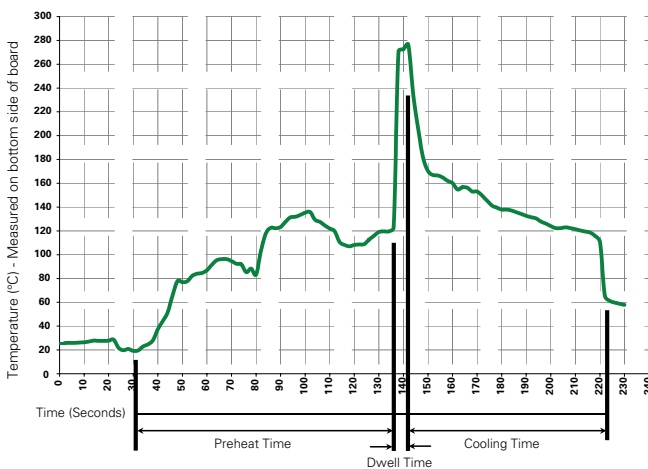


Soldering Parameters - Reflow Soldering (Surface Mount Devices)

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		10 – 30 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



Soldering Parameters - Wave Soldering (Thru-Hole Devices)



Recommended Process Parameters:

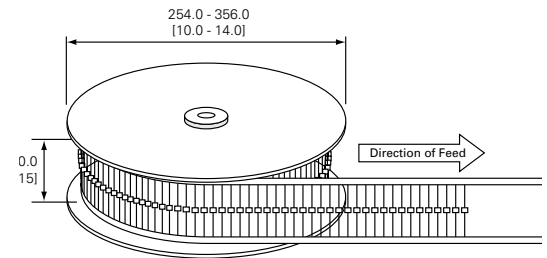
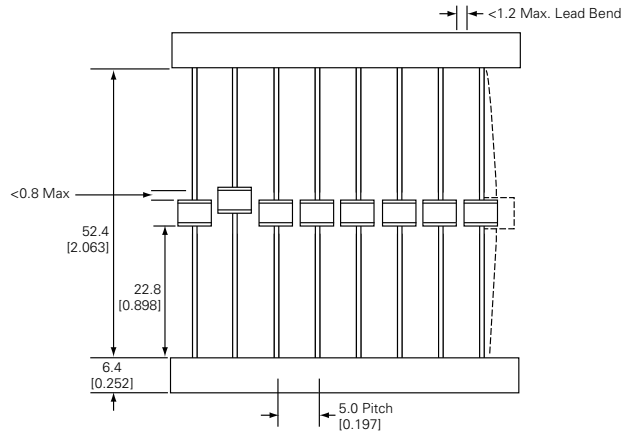
Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flux Activation Temperature) (Typical Industry Recommendation)	
Temperature Minimum:	100° C
Temperature Maximum:	150° C
Preheat Time:	60-180 seconds
Solder Pot Temperature:	280° C Maximum
Solder Dwell Time:	2-5 seconds

Soldering Parameters - Hand Soldering

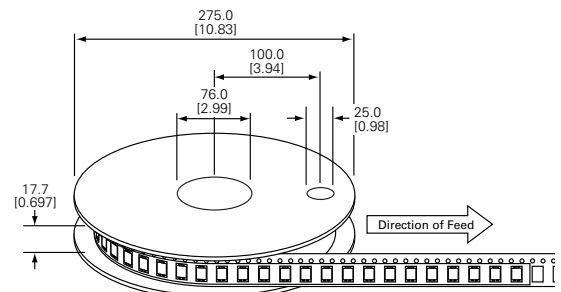
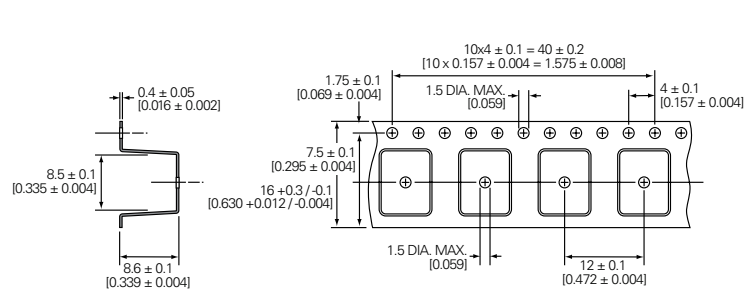
Solder Iron Temperature: 350° C +/- 5°C
Heating Time: 5 seconds max.

Packaging Dimensions

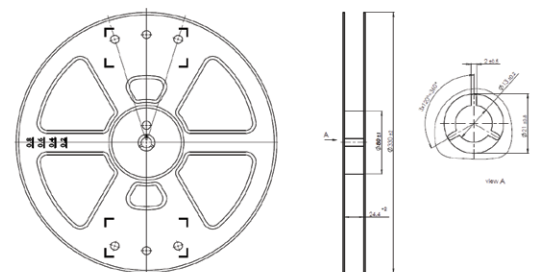
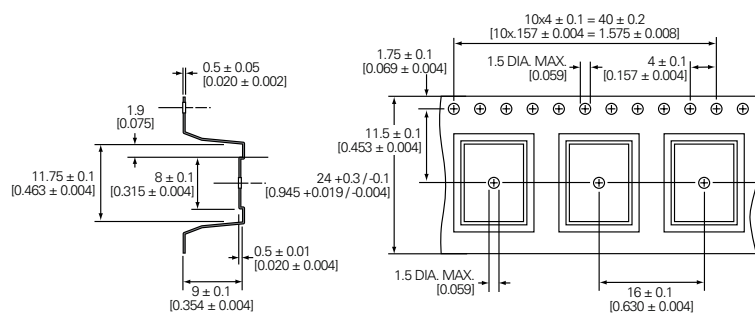
For 'L' Type Axial Lead Items



Core and 'MS' Type Items



For 'LS' Type Shaped Lead Items



Part Numbering System and Ordering Information

CG2 XXX XX * XX

Series

CG – for 75, 90, or 110V
CG2 – for 145V to 1000V

Breakdown Voltage

75	300
90	350
110	470
145	600
230	800
250	1000

Lead Option Code

(Blank) = No Leads / Core
L = Straight Leads
LS = Shaped Leads
MS = Surface Mount

Option Code*

SN = may have different DC Breakover Voltage Limit. Please refer to Electrical Characteristics table for additional information.

Packaging Option Code

(Blank) = No Leads / Core, Bulk Bag - 400 pcs
 L(Blank) = Straight Lead, Tray - 50 pcs
LTR = Straight Lead, Tape & Reel per EIA RS-296-E - 500 per reel
 LS(Blank) = Shaped Lead (see LS dimensions), Tape & Reel - 500 per reel

Examples:

CG75 – A non-leaded 75V device
CG2230L – A leaded 230V device
CG2800LTR – A leaded 800V device, tape-and-reel (per EIA standard RS-296-D)

Notes:

CG/CG2 devices with other breakdown voltages in the 75-1000 V range are available upon request.